



DM-OLED154-639

1.54" 128 x 64 Monochrome Graphic OLED Display Module-SPI



Contents

- 1 Revision History
- 2 Main Features
- 3 Pin Description
 - 3.1 Panel Pin Description
 - 3.2 Module Pin Description
- 4 Mechanical Drawing
 - 4.1 Panel Mechanical Drawing
 - 4.2 Module Mechanical Drawing
- 5 Electrical Characteristics
- 6 Optical Characteristics
- 7 AC characteristics
 - 7.1 Serial Interface Timing Characteristics (4-wire SPI)
 - 7.2 I2C interface characteristics
- 8 Power on/off sequence
- 9 Schematic
 - 9.1 Module schematic
 - 9.2 Application circuit for 4-wire SPI mode
 - 9.3 Application circuit for IIC mode
- 10 Command Table
- 11 Reliability
- Warranty and Conditions



1 Revision History

Date	Changes
2018-09-28	First release

2 Main Features

Item	Specification	Unit
Diagonal Size	1.54	inch
Display Mode	Passive Matrix OLED	-
Display Colors	Monochrome	Colors
Resolution	128 x 64	pixel
Controller IC	SPD0301	-
Interface	4wire SPI	-
Active Area	35.052 x 17.516	mm
Module Dimension	38.00 x 42.4	mm
Weight	TBD	g



3 Pin Description

3.1 Panel Pin Description

Pin No.	Symbol	Function Description					
1111100		Reserved Pin(Supporting	Pin)				
				m stresses on the			
1	N.C. (GND)	The supporting pins can reduce the influences from stresses on the function pins.					
•	14.C. (GIVD)	These pins must be conne	ected to external ground:	as the ESD protection			
		circuit.	ected to external ground	as the ESD protection			
		Ground of Analog Circui	f				
2	VLSS	This is an analog ground		ed to VSS externally			
		Ground of Logic Circuit	pin. it should be connect	ed to VBB externally.			
3	VSS		ets as a reference for the	logic nine. It must be			
3	V 33	VSS This is a ground pin. It acts as a reference for the logic pins. It must be connected to external ground.					
		Reserved Pin(Supporting					
		The supporting pins can		m strasses on the			
4	N.C. (GND)	function pins.	reduce the influences from	in stresses on the			
	N.C. (GND)	These pins must be conne	acted to external ground	os the ESD protection			
		circuit.	ected to external ground	as the ESD protection			
		Power Supply for Logic					
5	VDD	This is a voltage supply p	sin. It must be connected	to external source			
		Communicating Protocol		to external source.			
		This pins are MCU interf		ha following table:			
6		This phis are weed intern	BS1	BS2			
	BS1	IIC	_	0			
	BS2	4-Wire SPI	1	0			
7			0	-			
,		8-bit 80XX parallel	1	1			
		8-bit 68XX parallel	0	1			
	GG.	Chip Select		1.6 2.6011			
8	CS#	This pin is the chip selec		ed for MCU			
		communication only who					
0	DEC#	Power Reset for Controll					
9	RES#	This pin is reset signal input. When the pin is low, initialization of the chip is executed. Keep this pin pull high during normal operation.					
			n pull nigh during norma	operation.			
		Data/Command Control	1 4 1 2 3371 41				
		This pin is Data/Comman					
		input at D7~D0 is treated					
		input at D7~D0 will be to					
10	D/C#	When the pin is pulled high and serial interface mode is selected, the					
10	D/C#	at SDIN will be interpreted as data. When it is pulled low, the data at SDIN will be transferred to the command register. In I2C mode, this pulled low is pulled low.					
		acts as SA0 for slave	to the command register	. In 12C mode, this pin			
		address selection.					
			MCII interface signals r	please refer to the Timing			
		Characteristics Diagrams		hease refer to the Tilling			
		Read/Write Select or Wr					
		1		a to a 68VV somios			
		This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as Read/Write (R/W#) selection					
		input. Pull this pin to "H					
11	R/W#	1 1	ngn for read mode and	pun it to Low for			
11	K/ W#	write mode.	- d- (14, 1 d)	.:11 1 41 W.:'- (WD !/\			
		When 80XX interface me					
		input. Data write operation	on is initiated when this p	om is pulled low and the			
		CS# is pulled low.		4 1 1 4 V/QQ			
		When serial or I2C mode	is selected, this pin mus	t be connected to VSS.			



12	E/RD#	Read/Write Enable or Read This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled high and the CS# is pulled low. When connecting to an 80XX-microprocessor, this pin receives the Read (RD#) signal. Data read operation is initiated when this pin is pulled low and CS# is pulled low.
13-20	D0-D7	When serial or I2C mode is selected, this pin must be connected to VSS. Host Data Input/ Output Bus These pins are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When serial mode is selected, D1 will be the serial data input SDIN and D0 will be the serial clock input SCLK. When I2C mode is selected, D2 & D1 should be tired together and serve as SDAout & SDAin in application and D0 is the serial clock input SCL. Unused pins must be connected to VSS except for D2 in serial mode.
21	IREF	Current Reference for Brightness Adjustment This pin is segment current reference pin. A resistor should be connected between this pin and VSS. Set the current at 12.5 µ A maximum.
22	VCOMH	Voltage Output High Level for COM Signal This pin is the input pin for the voltage output high level for COM signals. A capacitor should be connected between this pin and VSS.
23	VCC	Power Supply for OEL Panel This is the most positive voltage supply pin of the chip. A stabilization capacitor should be connected between this pin and VSS when the converter is used. It must be connected to external source when the converter is not used.
24	N.C. (GND)	Reserved Pin(Supporting Pin) The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground as the ESD protection circuit.

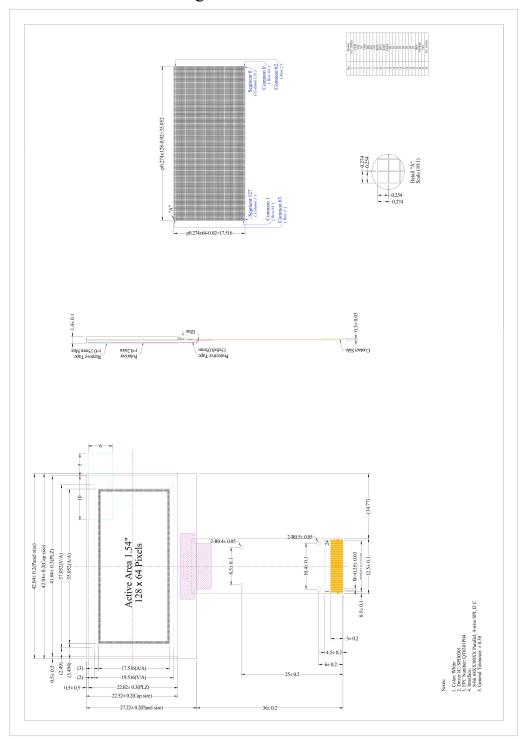
3.2 Module Pin Description

Pin No.	Symbol	Function Description
1	GND	Ground
2	VCC	Power Supply 3.3V
3	SCL	SPI Clock
4	SDA	SPI DATA
5	RES	OLED reset Pin.
6	D/C	Data/Command Control
0	D/C	This pin is Data/Command control pin.
7	CS	Chip Select
/	CS	This pin is pulled low to active. Connect to ground if no used .



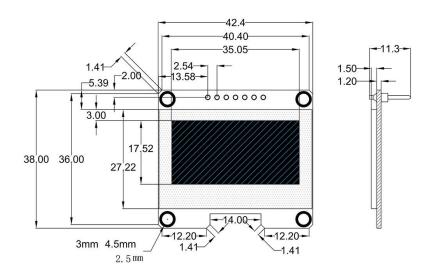
4 Mechanical Drawing

4.1 Panel Mechanical Drawing





4.2 Module Mechanical Drawing



5 Electrical Characteristics

Item	Symbol	Condition	Min	Тур.	Max	Unit
Power supply	VDD		2.6	3.3	3.5	V
Input Power	VCC IN		4.5		6.5	V
Supply Voltage for Display(for OLED Panel)	Vcc		11.5	12	12.5	V
Segment Output current consumption in Vcc	ISEG	Contrast max	280	310	340	uA
Operating Maximum Temperature	TOP		-40		70	°C
Storage Maximum Temperature	TST		-40		85	°C

6 Optical Characteristics

Item	Symbol	Min	Тур	Max	Unit
View Angles		160		-	0
Response Time (25°C)	Tr + Tf		30		ns
Brightness	Lbr	90	110	-	cd/m²
Dark room Contrast Ratio	CR	2000:1	-	-	

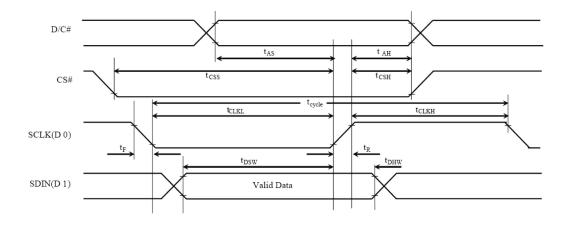


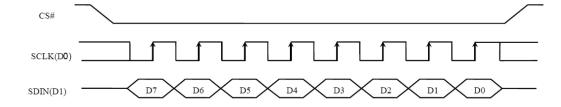
7 AC characteristics

7.1 Serial Interface Timing Characteristics (4-wire SPI)

Symbol	Description	Min	Max	Unit
t _{cycle}	Clock Cycle Time	250	-	ns
t _{AS}	Address Setup Time	150	-	ns
t _{AH}	Address Hold Time	150	-	ns
t _{CSS}	Chip Select Setup Time	120	_	ns
t _{CSH}	Chip Select Hold Time	60	_	ns
t _{DSW}	Write Data Setup Time	50	-	ns
t _{DHW}	Write Data Hold Time	15	_	ns
t _{CLKL}	Clock Low Time	100	_	ns
t _{CLKH}	Clock High Time	100	-	ns
t _R	Rise Time	-	15	ns
t _F	Fall Time	-	15	ns

^{*} $(V_{DD} - V_{SS} = 1.65V \text{ to } 3.3V, VDD=VDDIO, T_a = 25^{\circ}C)$



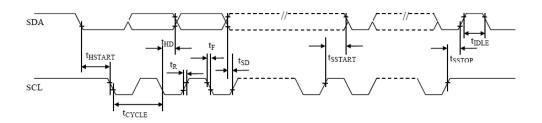




7.2 I2C interface characteristics

Symbol	Description	Min	Max	Unit
t _{cycle}	Clock Cycle Time	2.5	-	μs
t _{HSTART}	Start Condition Hold Time	0.6	_	μs
_	Data Hold Time (for "SDA _{OUT} " Pin)	0		
t _{HD}	Data Hold Time (for "SDA _{IN} " Pin)	300	_	ns
t _{SD}	Data Setup Time	100	_	ns
t _{SSTART}	Start Condition Setup Time (Only relevant for a repeated Start condition)	0.6	-	μs
t _{SSTOP}	Stop Condition Setup Time	0.6	-	μs
t _R	Rise Time for Data and Clock Pin		300	ns
t _F	Fall Time for Data and Clock Pin		300	ns
t _{IDLE}	Idle Time before a New Transmission can Start	1.3	_	μs

^{*} $(V_{DD} - V_{SS} = 1.65V \text{ to } 3.3V, T_a = 25^{\circ}C)$



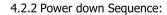


8 Power on/off sequence

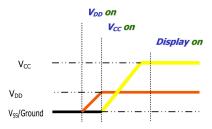
To protect OEL panel and extend the panel life time, the driver IC power up/down routine should include a delay period between high voltage and low voltage power sources during turn on/off. It gives the OEL panel enough time to complete the action of charge and discharge before/after the operation.

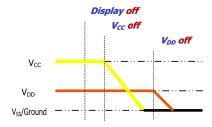
4.2.1 Power up Sequence:

- 1. Power up V_{DD}
- 2. Send Display off command
- 3. Initialization
- 4. Clear Screen
- 5. Power up V_{CC}
- 6. Delay 100ms (When V_{CC} is stable)
- 7. Send Display on command



- 1. Send Display off command
- 2. Power down V_{CC}
- 3. Delay 100ms (When V_{CC} is reach 0 and panel is completely discharges)
- 4. Power down V_{DD}





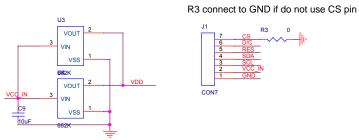
Note 13:

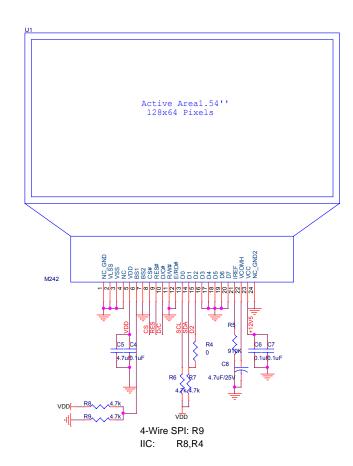
- 1) Since an ESD protection circuit is connected between V_{DD} and V_{CC} inside the driver IC, V_{CC} becomes lower than V_{DD} whenever V_{DD} is ON and V_{CC} is OFF.
- 2) V_{CC} should be kept float (disable) when it is OFF.
- 3) Power Pins (V_{DD} , V_{CC}) can never be pulled to ground under any circumstance.
- 4) V_{DD} should not be power down before V_{CC} power down.



9 Schematic

9.1 Module schematic

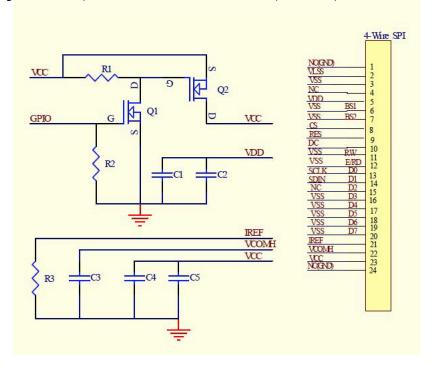






9.2 Application circuit for 4-wire SPI mode

(When design main board, Please add Electronic Switch circuit, otherwise, will be caused leak current)



Recommended Components:

C1, C2: 1μ F / 16V, X5R C3: 2.2μ F /25V C4: 4.7μ F / 25V, X7R C5: 0.1μ F / 25V, X7R

R1, R2: 47kΩ

R3: $910K\Omega$, R3 = (Voltage at IREF - VSS) / IREF

Q2: FDN338P Q1: FDN335N

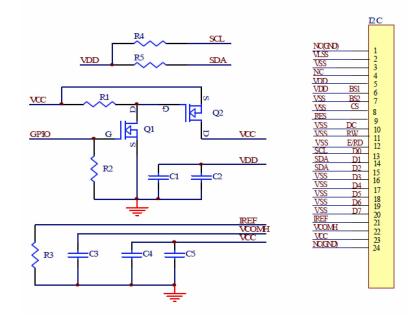
Notes:

VDD: 1.65V~3.3V VCC_IN: 11.5~12.5V

9.3 Application circuit for IIC mode



(When design main board, Please add Electronic Switch circuit, otherwise, will be caused leak current)



Recommended Components:

C1, C2: $1\mu F / 16V$, X5R C3: $2.2\mu F / 25V$ C4: $4.7\mu F / 25V$, X7R C5: $0.1\mu F / 25V$, X7R

R1, R2: $47k\Omega$

R3: $910K\Omega$, R3 = (Voltage at IREF - VSS) / IREF

R4, R5: 4.7kΩ Q2: FDN338P Q1: FDN335N

Notes:

VDD: 1.65V~3.3V VCC_IN: 11.5~12.5V

The I^2C slave address is 0111100b'. If the customer ties D/C# to VDD, the I^2C slave address will be

0111101b'.

10 Command Table

Please check in driver IC DATASHEET

11 Reliability

Test Item	Content of Test	Test Condition	Note
High Temperature Storage	Endurance test applying the high storage	85°C	2



	temperature for a long time.	200hrs	
Low Temperature Storage	Endurance test applying the high storage	-40°C	1.2
	temperature for a long time.	200hrs	1,2
High Temperature	Endurance test applying the electric stress	70°C	
Operation	(Voltage & Current) and the thermal stress	200hrs	-
	to the element for a long time.		
Low Temperature	Endurance test applying the electric stress	-40 °C	1
Operation	under low temperature for a long time.	200hrs	1
High Temperature/	The module should be allowed to stand at	60°C,90%RH	
Humidity Operation	60°C,90%RH max, for 96hrs under no-load	96hrs	
	condition excluding the polarizer. Then		1,2
	taking it out and drying it at normal		
	temperature.		
Thermal Shock Resistance	The sample should be allowed stand the	-40°C/85°C	
	following 10 cycles of operation	10 cycles	
	-40°C 25°C 85°C√		
			-
	20i 20i-		
	30min 5min 30min-		
	1 cycle₽		
Vibration Test	Endurance test applying the vibration during	Total fixed	
	transportation and using	amplitude:	
		15mm; Vibration:	
		10~55Hz;	
		One cycle 60	3
		seconds to 3	
		directions of X,	
		Y, Z, for each 16	
		minutes.	
Static Electricity Test	Endurance test apply the electric stress to	VS=800V,	
	the terminal.	RS=1.5k Ω ,	_
		CS=100pF,	_
		1 time.	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal. Temperature and humidity after remove from the rest chamber.

Note3: Test performed on product itself, not inside a container.

12 Warranty and Conditions

http://www.displaymodule.com/pages/faq HYPERLINK

"http://www.displaymodule.com/pages/faq"